

Derwent Class: A14; A21; A85; L03; P73; V04  
International Patent Class (Main): B32B-027/18; H05K-001/03  
File Segment: CPI; EPI; EngPI

?

LOW; COST; PRINT; CIRCUIT; BOARD;  
INTERMEDIATE; LAYER; NONWOVEN; GLASS; FIBRE; IMPREGNATE; THERMOSETTING;  
RESIN; FILL; BEND; STRENGTH

Index Terms/Additional Words: PCB

Derwent Class: A32; A85; A94; L03; P42; P73; V04

International Patent Class (Main): B29C-070/02; B32B-027/02; B32B-027/04;  
B32B-027/38

International Patent Class (Additional): B32B-017/04; B32B-031/12

File Segment: CPI; EPI; EngPI

?